

Notice of References Cited	Application/Control No. 09/815,446		Applicant(s)/Patent Under Reexamination BODE ET AL.	
	Examiner Dwin M. Craig		Art Unit 2123	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,372,395 B2	04-2002	Kawakubo et al.	430/22
*	B	US-5,243,195 A	09-1993	Nishi, Kenji	250/548
*	C	US-4,397,543	08-1983	Kolbe et al.	355/40
*	D	US-6,587,744 B1	07-2003	Stoddard et al.	700/121
*	E	US-6,163,366 A	12-2000	Okamoto et al.	355/53
*	F	US-5,438,413 A	08-1995	Mazor et al.	356/508
*	G	US-5,444,538 A	08-1995	Pellegrini, Joseph C.	356/401
*	H	US-6,699,627 B2	03-2004	Smith et al.	430/22
*	I	US-5,989,761 A	11-1999	Kawakubo et al.	430/22
*	J	US-6,445,206 B1	09-2002	Montull et al.	324/765
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)			
	U	Pete Klimecky, Craig Garvin, Cecilia G. Galarza, Brook S. Stutzman, Pramod P. Khargonekar and Fred L. Terry, Jr., "Real-Time Reactive Ion Etch Metrology Techniques to Enable In Situ response Surface Process Characterization" 9/4/2000, 7 pages.			
	V	Terrence E. Zavec, Rene Blanquies, "Predictive process control for sub-0.2 um lithography" SPIE, March 2000, pages 1-12.			
	W				
	X				

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.